

注記 NOTES

1. 嵌合相手: 52465,52588 シリーズ
MATE WITH : 52465,52588 SERIES
2. ウェハーの ② から隣接するピンの ② 迄の位置を示す。
SHOW POSITION FROM ② OF WAFER TO ② OF ADJACENT PINS.
3. 本製品は 53309-**27 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-**27

0.4	17.8	16.9	15.2	53309-4029	40
0.8	17.0	16.1	14.4	-3829	38
0.4	16.2	15.3	13.6	-3629	36
0.8	15.4	14.5	12.8	-3429	34
0.4	14.6	13.7	12.0	-3229	32
0.8	13.8	12.9	11.2	-3029	30
0.4	13.0	12.1	10.4	-2829	28
0.8	12.2	11.3	9.6	-2629	26
0.4	11.4	10.5	8.8	-2429	24
0.8	10.6	9.7	8.0	-2229	22
0.4	9.8	8.9	7.2	-2029	20
0.8	9.0	8.1	6.4	-1829	18
0.4	8.2	7.3	5.6	-1629	16
0.8	7.4	6.5	4.8	-1429	14
0.4	6.6	5.7	4.0	-1229	12
0.8	5.8	4.9	3.2	53309-1029	10

REVISED	EC NO: J2010-1285	2009/12/17	DRAWN:YON002	CHKD:SMARUYAMA	2009/12/17	APPR:SMARUYAMA	2009/12/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION									
									10 UNDER	±0.2	DRAWN BY M.NINOMIYA	DATE 2004/03/10	TITLE 0.8 B/B CONN.WAFER ASS'Y R/A SMT(WITHOUT BOSS)											
									10 OVER 30 UNDER	±0.25	CHECKED BY K.TOJO	DATE 2004/03/10												
									30 OVER	±0.3	APPROVED BY M.SASAO	DATE 2004/03/10												
									ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.									
									DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-53309-011		1 OF 2									
									REV								THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

10 9 8 7 6 5 4 3 2 1

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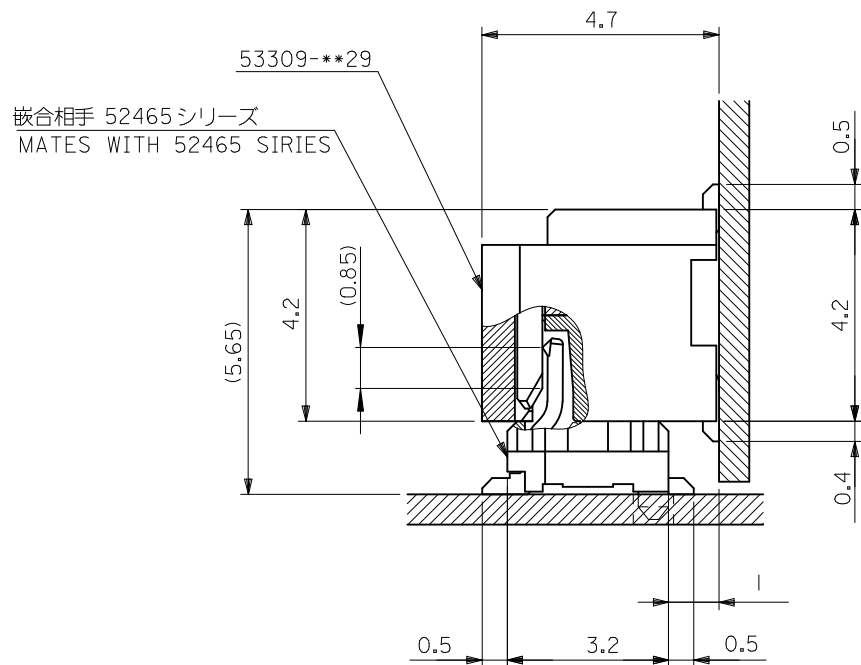
E

D

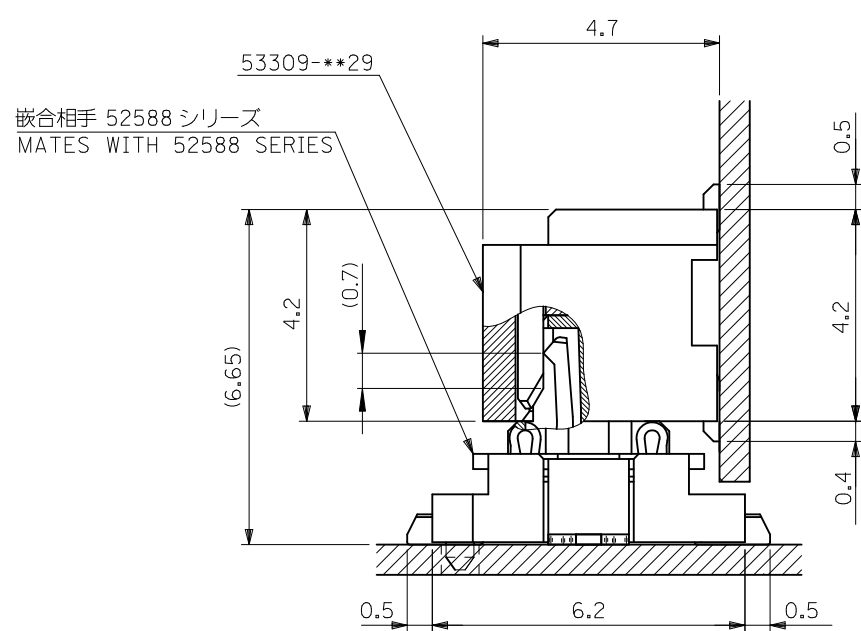
C

B


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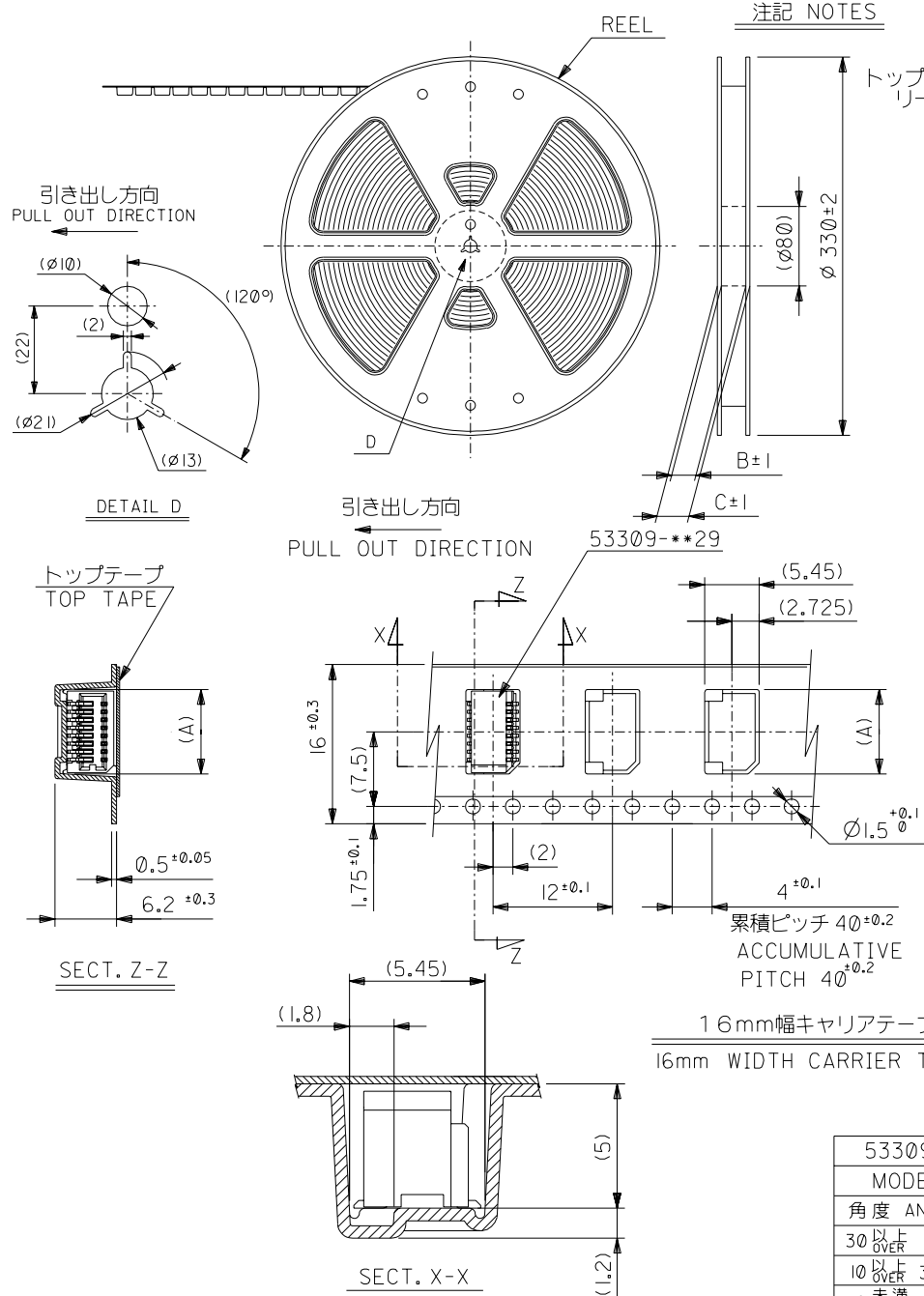


嵌合状態図 (参考)
MATED DRAWING(REF.)



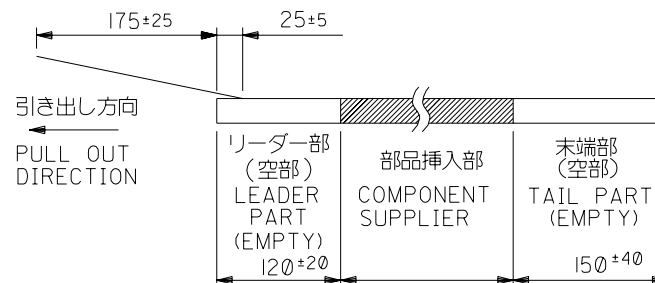
嵌合状態図 (参考)
MATED DRAWING(REF.)

REVISED EC NO: J2010-1285 DRWN: YON002 CHKD: SMARUYAMA APPR: SMARUYAMA 2009/12/17 2009/12/17 2009/12/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY M. NINOMIYA	DATE 2004/03/10	TITLE 0.8 B/B CONN. WAFER ASS'Y R/A SMT(WITHOUT BOSS)			
		10 OVER 30 UNDER	± 0.25	CHECKED BY K. TOJO	DATE 2004/03/10				
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2004/03/10	MOLEX INCORPORATED			
		ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-53309-011		SHEET NO. 2 OF 2	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
	B	REV							



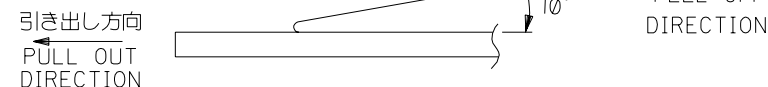
注記 NOTES

1. 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH
- トップテープ TOP TAPE
リーダー部 LEADER PART
未接着部 NON-BONDED PART



3. トップテープの剥離強度：(剥離方向は下図参照)
0.1N \sim 1.3N(10gf \sim 130gf) 尚、本規格値は、出荷時に適用。
(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1N \sim 1.3N(10gf \sim 130gf) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



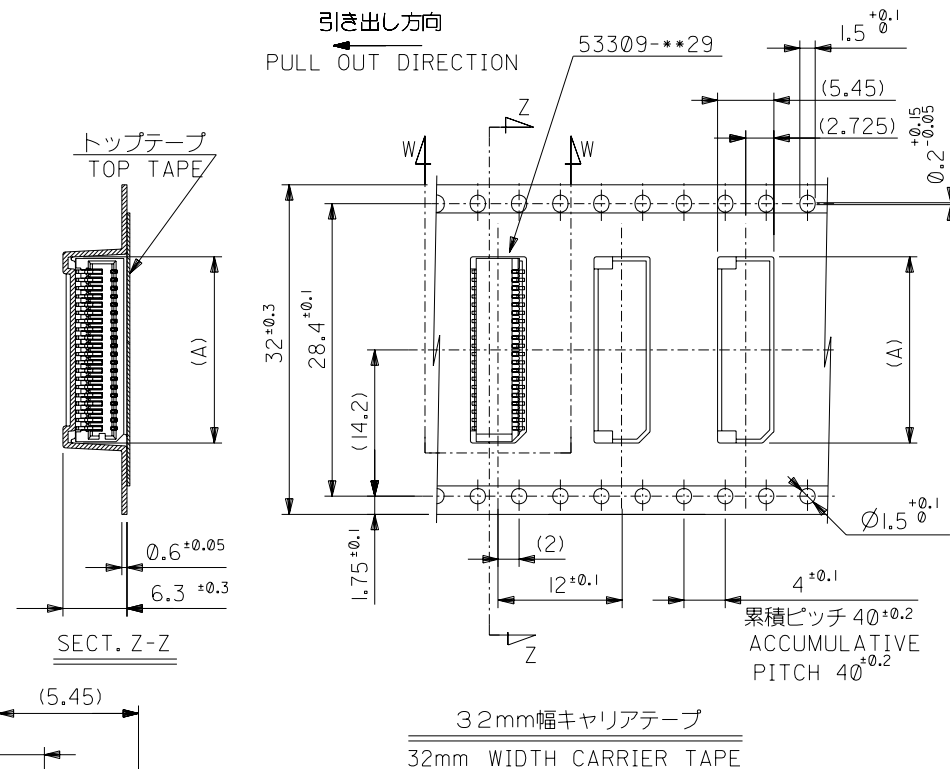
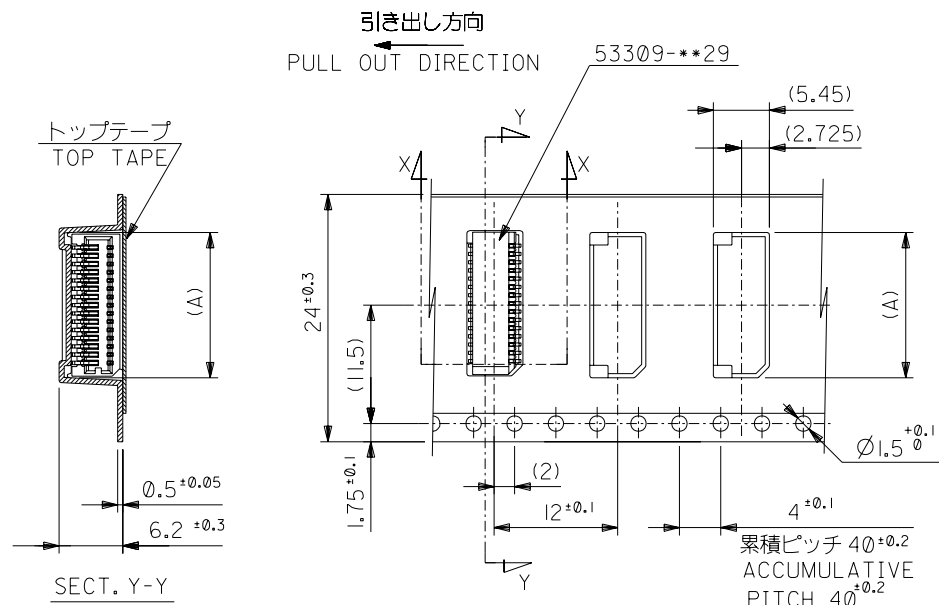
4. 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS)
MATERIAL
<リサイクル材を含む>

CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>

5. 本製品は 53309-**91 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-**91.

16	21.4	17.4	9.3	53309-1870	18
			8.5	53309-1670	16
			7.7	53309-1470	14
			6.9	53309-1270	12
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	6.1	53309-1070	10
			(A)	MATERIAL NO.	極数 CIRCUIT

53309-**70		材料 MATERIAL		注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
MODEL NO.		仕上げ FINISH		—		REVISE ONLY ON CAD SYSTEM	
角度 ANGLE		適用電線範囲 WIRE RANGE		—		TITLE 名称 0.8 BtB Conn Wafer Assy	
30以上 OVER		被覆外径 INS. RANGE		—		RA SMT Without Boss	
10以上 30未満 OVER UNDER		DRAWN BY 04/03/10 M.NINOMIYA		CHK'D BY 04/03/10 K.TOJO		Embstp Pkg	
10未満 UNDER		DR. 04/03/10 M.SASAO		DATE		-LEAD FREE-	
一般公差 GENERAL TOLERANCES		記号 LTR		変更内容 REVISION RECORD		尺度 SCALE	
		DR. CHK.		DATE		DWG. NO. (SHEET 1 OF 2)	
						SD-53309-012	
						REV	
						0	



24	29.4	25.4	16.5	53309-3670	36
			15.7	53309-3470	34
			14.9	53309-3270	32
			14.1	53309-3070	30
			13.3	53309-2870	28
			12.5	53309-2670	26
			11.7	53309-2470	24
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	10.9	53309-2270	22
			10.1	53309-2070	20
			(A)	MATERIAL NO.	極数 CIRCUIT

53309-**-70		材料 MATERIAL		SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
MODEL NO.		仕上げ FINISH		—		REVISE ONLY ON CAD SYSTEM	
角度 ANGLE		適用電線範囲 WIRE RANGE		—		TITLE 名称 0.8 BtB Wafer Assy RA SMT Without Boss Embstp Pkg -LEAD FREE-	
30 以上 OVER		被覆外径 INS. RANGE		—		DWG. NO. (SHEET 2 OF 2)	
10 以上 30 未満 OVER UNDER		DRAWN BY '04/03/10 M.NINOMIYA		CHK'D BY '04/03/10 K.TOJO		REV	
10 未満 UNDER		DR. 日付 CHK. DATE		APP'D BY '04/03/10 M.SASAO		SD-53309-012	
一般公差 GENERAL TOLERANCES		記号 LTR		変更内容 REVISION RECORD		0	